

PC3001

Conductive Adhesive

Description

PC3001 is a thermosetting, one-component, solvent-free, silver-filled epoxy conductive adhesive, designed for the connection of electronic (SMDs) and bare dies with LTCC and ceramic substrates.

Key Features

- High electrical and thermal conductivity
- Very low degassing
- High reliability



This picture does not show the packaging of PC3001 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Physical Properties

Processing Life (h)	Approx. 20
Curing Profile	10 min / 150 °C 20 min / 120 °C
Substrate and Components	Substrate Materials: LTCC, Al ₂ O ₃ – Ceramic, lead frames and flexible substrates
Adhesion (N / mm ²) Standard: DIN EN 1465	Min. 8
Weight Loss during Curing Process at 150 °C (%)	Max. 1.2
Glass Transition Temperature (°C)	Approx. 38
Thermal Conductivity (W/mK)	Min. 5
Volume Resistivity (mΩ.cm)	Max. 0.3
Applications	Dispensing Jetting
Compliant Products	SMT Adhesive: PD955 M
Halogen	
Halogen content	Hydrolyse Halogen
Tolerance	Halogen < 50 ppm

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Adhesive Conditioning

- Remove adhesive from freezer: Before opening the package leave it for at least 2 hours at room temperature so that adhesive heats up
- Do not open jar/cartridge while adhesive is cold to prevent condensation
- Do not use faster defrost systems

Cleaning Instructions

The uncured adhesive can be removed with Zestron HC and other Zestron and Vigon cleaning materials. The cleaned parts must be completely dry before installing them in the machine. Defective components can be removed by heating the cured adhesive joint with hot air above 250°C. The hot remaining adhesive can be removed with a sharp tool.

Storage Conditions

- Store the adhesive in tightly sealed containers and avoid exposure to high humidity and sunlight
- Store cartridges with tip pointing downwards
- Max. expiration date: Shelf life: Please refer to the expiry date on the label of the packaged product
- Storage condition in the freezer at – 40 °C

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